

Martin Springer

List of Publications by Year in descending order

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Version: 2024-02-01

14
papers

115
citations

1307594

7
h-index

1372567

10
g-index

14
all docs

14
docs citations

14
times ranked

104
citing authors

#	ARTICLE	IF	CITATIONS
1	Fatigue life predictions of metal structures based on a low-cycle, multiaxial fatigue damage model. International Journal of Fatigue, 2018, 116, 355-365.	5.7	25
2	A thermo-mechanical cyclic cohesive zone model for variable amplitude loading and mixed-mode behavior. International Journal of Solids and Structures, 2019, 159, 257-271.	2.7	21
3	Viscoelastic Material Characterization and Modeling of Photovoltaic Module Packaging Materials for Direct Finite-Element Method Input. IEEE Journal of Photovoltaics, 2020, 10, 1424-1440.	2.5	18
4	Linear viscoelastic characterization of electrically conductive adhesives used as interconnect in photovoltaic modules. Progress in Photovoltaics: Research and Applications, 2020, 28, 659-681.	8.1	14
5	Environmental influence on cracking and debonding of electrically conductive adhesives. Engineering Fracture Mechanics, 2021, 241, 107398.	4.3	8
6	Employing Weibull Analysis and Weakest Link Theory to Resolve Crystalline Silicon PV Cell Strength Between Bare Cells and Reduced- and Full-Sized Modules. IEEE Journal of Photovoltaics, 2021, 11, 731-741.	2.5	8
7	Multiscale Modeling of Shingled Cell Photovoltaic Modules for Reliability Assessment of Electrically Conductive Adhesive Cell Interconnects. IEEE Journal of Photovoltaics, 2021, 11, 1040-1047.	2.5	8
8	Failure Analysis of a New Polyamide-Based Fluoropolymer-Free Backsheet After Combined-Accelerated Stress Testing. IEEE Journal of Photovoltaics, 2021, 11, 1197-1205.	2.5	7
9	Environmental Influence on Fracture and Delamination of Electrically Conductive Adhesives. , 2020, , .		2
10	On Residual Stresses and Reference Temperatures in Thermomechanical Simulations of Photovoltaic Modules Using the Finite Element Method. IEEE Journal of Photovoltaics, 2022, 12, 853-859.	2.5	2
11	A thermo-mechanical fatigue damage modeling methodology for power semiconductor robustness validation studies. , 2018, , .		1
12	Combined simulation of fatigue crack nucleation and propagation based on a damage indicator. Frattura Ed Integrita Strutturale, 2016, 10, 155-161.	0.9	1
13	Fatigue crack growth modeling in the metallization of power semiconductors under cyclic thermo-mechanical loading. , 2016, , .		0
14	Representative Modules for Accelerated Thermal Cycling and Static Load Testing. , 2021, , .		0